

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : F. Farassat ) Group Art Unit Unknown  
 Appl. No. : Unknown )  
 Filed : Herewith )  
 For : MECHANISM FOR )  
 EXCHANGING CHIP- )  
 CARRIER PLATES FOR USE )  
 IN A HYBRID CHIP- )  
 BONDING MACHINE )  
 Examiner : Unknown )

*6/a*

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents  
 Washington, D.C. 20231

Dear Sir:

Prior to examination, please amend the above referenced application as follows:

IN THE ABSTRACT:

Please amend the abstract as follows:

Abstract of the Disclosure

A mechanism for exchanging chip-carrier plates in a hybrid chip-bonding machine having a plurality of chip-carrier plates, a magazine to store the plurality of chip-carrier plates, and a transport arrangement having a first and second clamping device that are disposed on a movable holder is disclosed. The transport arrangement is designed to remove a selected chip-carrier plate from the magazine and deliver it to a chip processing station. After processing, the selected chip-carrier plate is removed and deposited in the magazine. Movement of the chip-carrier plates is controlled such that the selected chip-carrier plate is positioned at a collection point to be collected from the magazine. Movement of the transport arrangement holder is controlled such that the first and second clamping devices are disposed in a vertical arrangement